3DLevelScanner





Technical Data Sheet

APM's 3DLevelScanner™ incorporates advanced acoustic technology for accurately measuring bulk solids based on multiple point measurement and surface visualization of all kinds of silos and open bins.

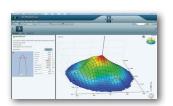


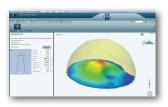
Theory Of Operation

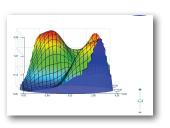
The APM 3DLevelScanner is the only device presently available that delivers accurate measurement of bulk solids and powders - based on multiple point measurement and surface visualization regardless of the type of material or product characteristics, type and size of storage silo, bin or container, and harshness of the storage environment. The 3DLevelScanner employs an array of three antennas to transmit low frequency pulses and to receive echoes of the pulses from the contents of the vessel. Using three antennas the unit measures not only the time/distance of each echo but also its direction. The device's Digital Signal Processor samples and analyzes the received signals to provide very accurate measurements of the level and volume of the stored contents, and generates a 3D representation of actual allocation of product within the container for display on remote computer screens. It incorporates APM's unique dust-penetrating technology to achieve an unrivalled degree of process measurement and inventory control.

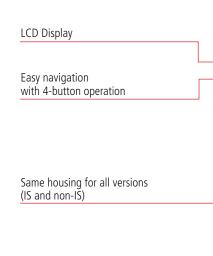
3D Mapping

This unique device measures practically any kind of material stored in a large variety of containers, including silos, large open bins, bulk solid storage rooms, stockpiles and warehouses. It maps build-up and other irregularities that randomly form over time, offering solutions for this and many other previously inaccessible challenging applications.















Preferred application:	Solids		
Measuring range:	70 m (230 ft)		
Process fitting:	Thread, Mounting Plate, Angel Adaptor		
Process temperature, 2 models:	standard -40° 85° C high temp40°180° C		
Process pressure:	-0.023 bar (–0.2943.5 Psi)		
Communication:	420mA/RS485/Modbus		
Emitting frequency:	2 KHz to 7 KHz		

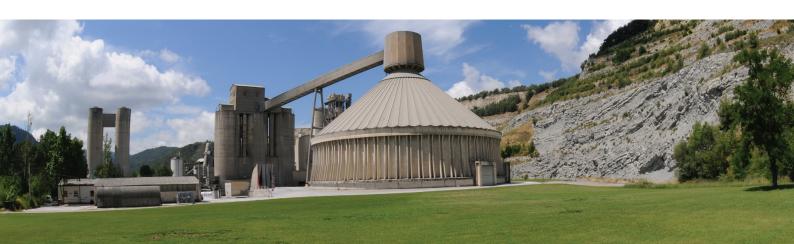




Materials		
Housing		Painted aluminum die casting
Inspection window in housing		Polycarbonate
Antenna		Painted aluminum die casting / Teflon (PTFE)
Weight		
3DLevelScanner		5.6 Kg (12.35 lb)
Output variable		
Output signal		Active 420mA/RS485/Modbus
Resolution		10 μΑ
Fault signal		Current output unchanged, 22 mA, >3.6 mA (adjustable)
Current limitation		22 mA
Maximal Load		400 Ohm
Communication		
Туре		RS485/Modbus
Ambient conditions		
Ambient, storage and transport temperature		-4085°C (-40+185°F)
Process conditions		
Vessel pressure		0.023 bar (-0.2943.5 PSI)
Process temperature		
Measured on the process fitting		-40+180°C (-40+350°F)
Vibration resistance		Mechanical vibrations with 2g and 5200 Hz
Electromechanical data		
Cable entry/plug		1 x M20x1.5 (cable-Ø 812mm), 1 x blind stopper M20x1.5
	Or	2 x cable entry ½" NPT
Display panel		
LCD		4 lines x 20 characters
Adjustment elements		4 keys

Technical Data

Power supply – 4-wire instrument (Activ	/e) 420 mA
Supply voltage	1832 VDC
Power consumption	max 1.5 W @ 24VDC
Electrical protective measures	
Protection	IP66, IP67 according to IEC 60529
Approvals	
ATEX	ATEX II 1/2D, 2D, Ex ibD/iaD 20/21 T110°C
	ATEX II 2G Ex ia/ib IIB T4
cFMus	Intrinsically Safe CL I,II, DIV I, GP CDEFG
IECEx	Ex ib [ia] IIB T4 Gb (-40 $^{\circ}$ C < Ta < +85 $^{\circ}$ C)
	Ex ib [ia] IIIC T110°C Da/Db (-40 °C < Ta <+85 °C)
INMETRO	Ex ib [ia] IIB T4 Gb (- 40 $^{\circ}$ C $<$ Ta $<$ + 85 $^{\circ}$ C) Ex ib [ia]
	IIIC T110 °C Da/Db (- 40 °C < Ta < + 85 °C)
EAC	I Ex ib [ia] IIB T4 Gb X
	Ex ib [ia] IIIC T1 110°C Da/DbX
NEPSI	II 2G Ex ia/ib IIB T4
PESO (India)	Ex ib {ia} IIB t4 Gb
	FCC 47 CFR part 15:2007, subpart B, class A
KTL (Korea)	Ex ib [ia] IIB T4 Gb, Ex ib [ia] IIIC T1100C Da/Db
CE	
EMC	
Emission	EN 61326:1997 (class B)
Susceptibility	IEC / EN 61326:1997 + A1:1998 + A2:2001 + A3:2003
NSR (73/23/EWG)	EN 61010-1:2001
FCC	
Conformity	Part 15 of the FCC regulations
	FCC 47 CFR part 15:2007, subpart B, class A
Measurement characteristics	
Frequency	2 KHz to 10 KHz
Beam angle	30 - 70 degrees
Volume Accuracy	Maximal potential volumetric error out of total vessel capacity



<3%

Electrical Connection

General Requirements

In hazardous areas you should take note of the appropriate regulations, conformity and type of approval certificates of the sensors and power supply units.

When multiple scanners and/or 3DLinkPro are connected with the same power supply, the total power consumption should be taken into account.

4...20 mA 4-wire

Power supply and signal current are carried on two separate connection cables. The output signal is active, hence the PLC must be configured passive.

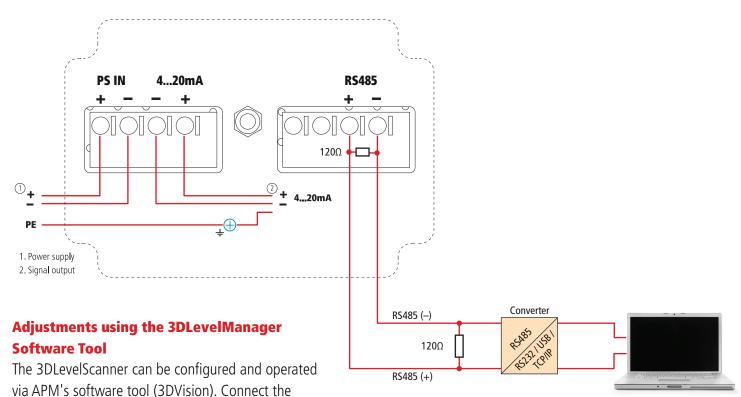
Connection Cable

RS485 cables should be shielded, twisted pair with 120 Ohm impedance, terminated by 120 Ohm resistors on both ends.

Avoid star topology wiring when connecting multiple scanners with on RS485 bus.

An outer cable diameter of 8 ...12 mm ensures the seal effect of the cable entry. If electromagnetic interference is expected, we recommend the use of screened cable for the signal lines.

Wiring Plans



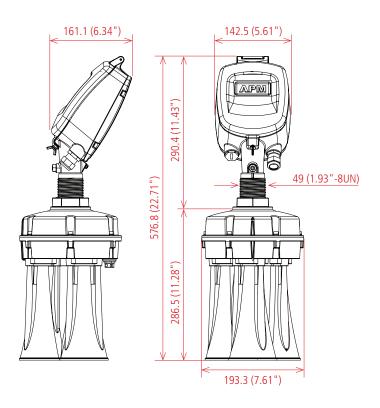
The drawing is not for IS applications

3DLevelScanner according to the above diagram.

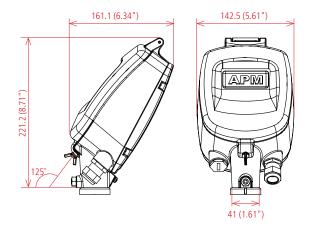
Dimensions

3DLevelScanner

with horn antenna in threaded version

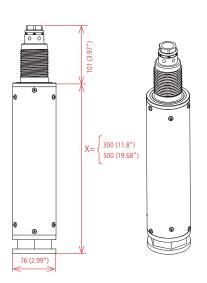


3DLevelScanner Housing

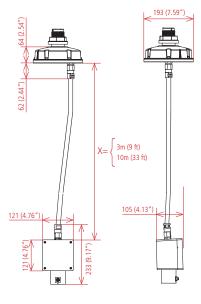


Accessories

Neck Extension



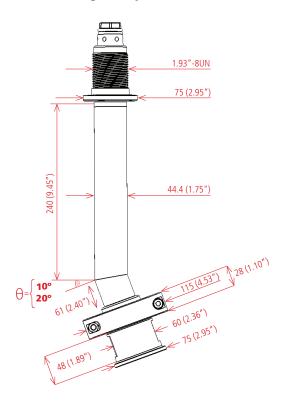
Head Body Separation Kit



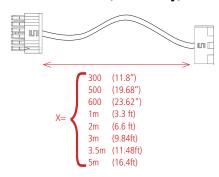
Dimensions in mm (inch)

3DLevelScanner

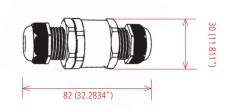
Angle Adaptor



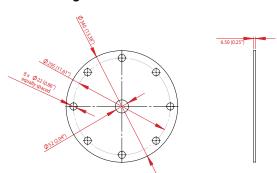
Cable Extention (for T0 only)

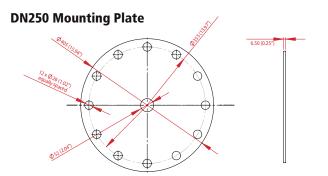


Cable Extention Conector



DN200 Mounting Plate





* DN100 and DN200 are also available

3DLevelScanner

Type

For solid applications

For solid applications with mapping capabilities M-**MV**- For solid applications with mapping capabilities

and visualization graphics tool

MVL- MV for multiple scanner connection



ATEX II 1/2D, 2D, Ex ibD/iaD 20/21 T110°C

- ATEX II 2G Ex ia/ib IIB T4

DX FM / cFMus Intrinsically Safe CL I,II, DIV I, GP CDEFG

 NEPSI II 2G Ex ia/ib IIB T4

- NEPSI II 1/2D Ex ibD/iaD 20/21 T110°C

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- IIIC T110 °C Da/Db (- 40 °C < Ta < + 85 °C) - EAC I Ex ib [ia] IIB T4 Gb X

Ex ib [ia] IIIC T1 110°C Da/DbX

KTL (Korea) Ex ib [ia] IIB T4 Gb, Ex ib [ia] IIIC T1100C Da/Db

Material / Finish

B – With horn antenna @195mm/ALU

C - With horn antenna @195mm/ALU Teflon Coated

Process connection

GD - Thread 1.93" - 8 UN

Electronics

V - 4 ...20mA - 4-wire/RS485/Modbus

Cable entry

M - M20x1.5 / 1/2" NPT

Temperature

T0 -Standard Version Suitable For 85°C (185°F)

T3 -Suitable For 180°C (356°F)

T3C -Suitable For 180°C (356°F)

Including Extended Cable L=30Cm (11.8")

Suitable For 180°C (356°F) **T**3D -

Including Extended Cable L=50Cm (19.7")

T3E – Suitable For 180°C (356°F)

Including Extended Cable L=1m (3' 3")

T3F – Suitable For 180°C (356°F) Including Extended Cable L=1.5m (4' 11")

T3G – Suitable For 180°C (356°F)

Including Extended Cable L=2m (6' 7")

T3I -Suitable For 180°C (356°F)

Including Extended Cable L=5m (16' 5")

T3x10 – Suitable For 180°C (356°F)

Including Extended Cable L=10m (32 10")

3DLevelScanner

Represented by













